



SOT684-19(D)

HVQFN56, thermal enhanced very thin quad flat package, no leads, 56 terminals, 0.1 mm dimple wettable flank, 0.5 mm pitch, 8 mm x 8 mm x 0.9 mm body

5 August 2021

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN56
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	29-06-2021
Manufacturer package code	98ASA01030D

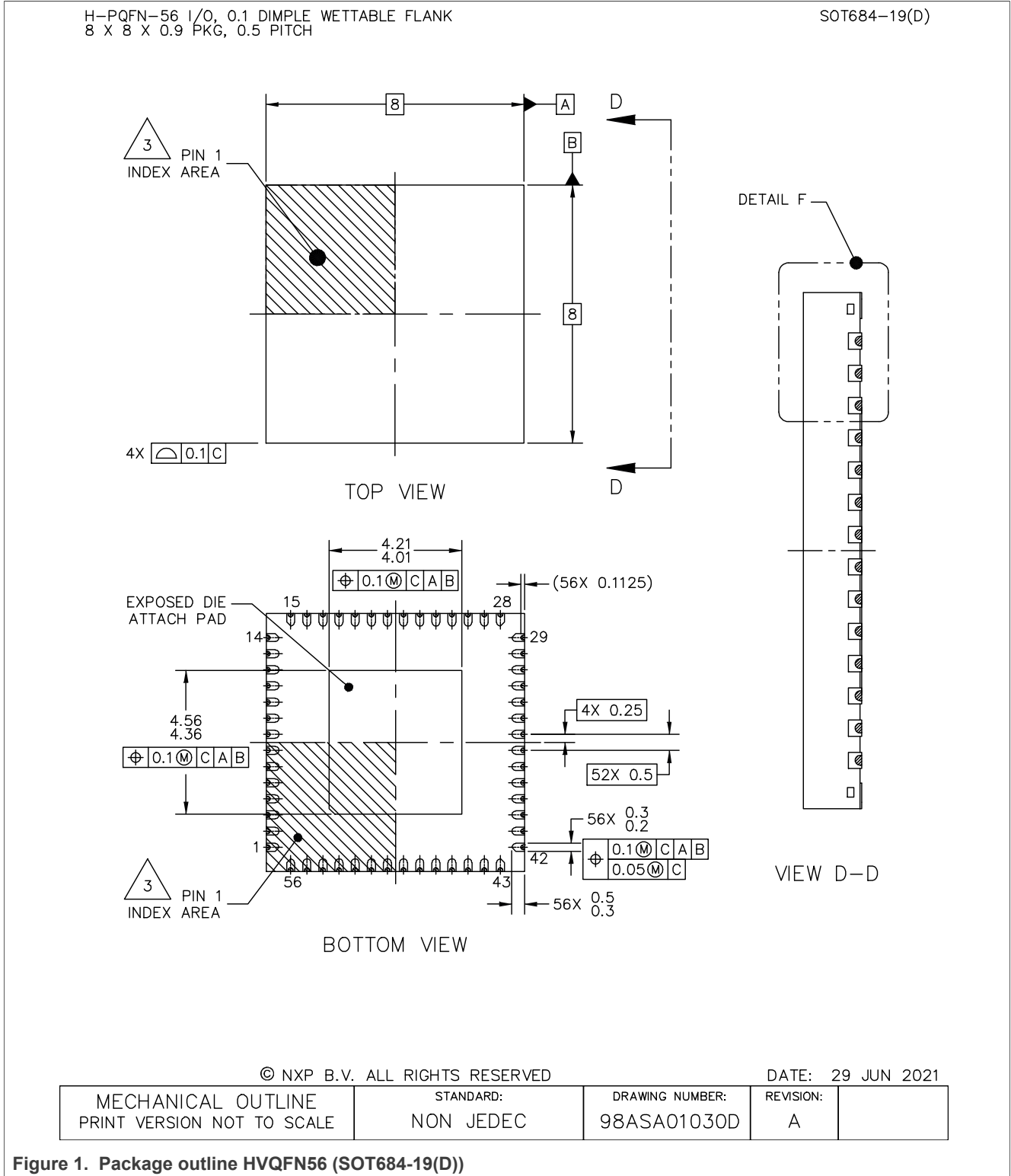
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	7.9	8	8.1	mm
package width	7.9	8	8.1	mm
package height	0.8	0.9	1	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	56	-	



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2 Package outline



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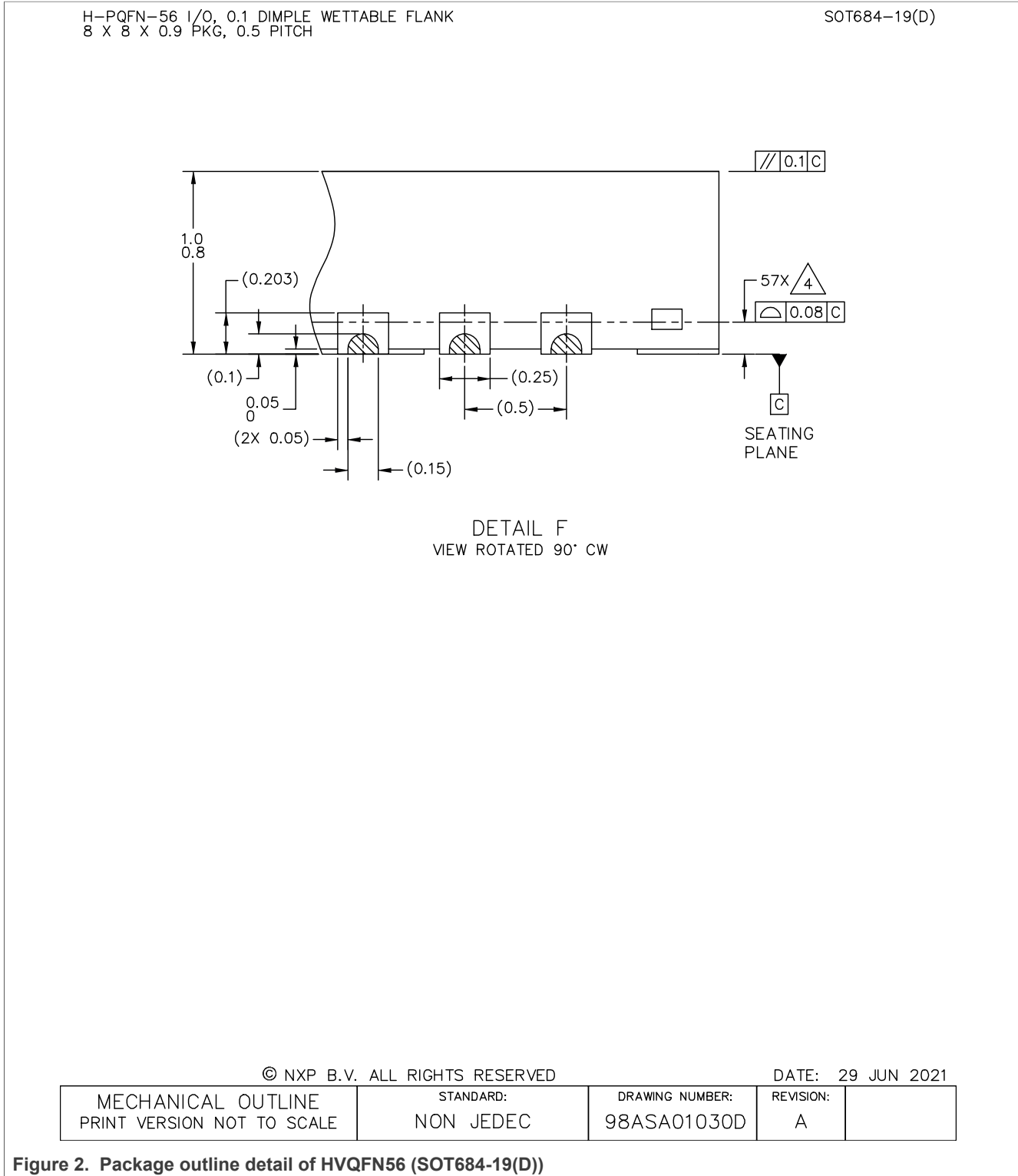


Figure 2. Package outline detail of HVQFN56 (SOT684-19(D))

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3 Soldering

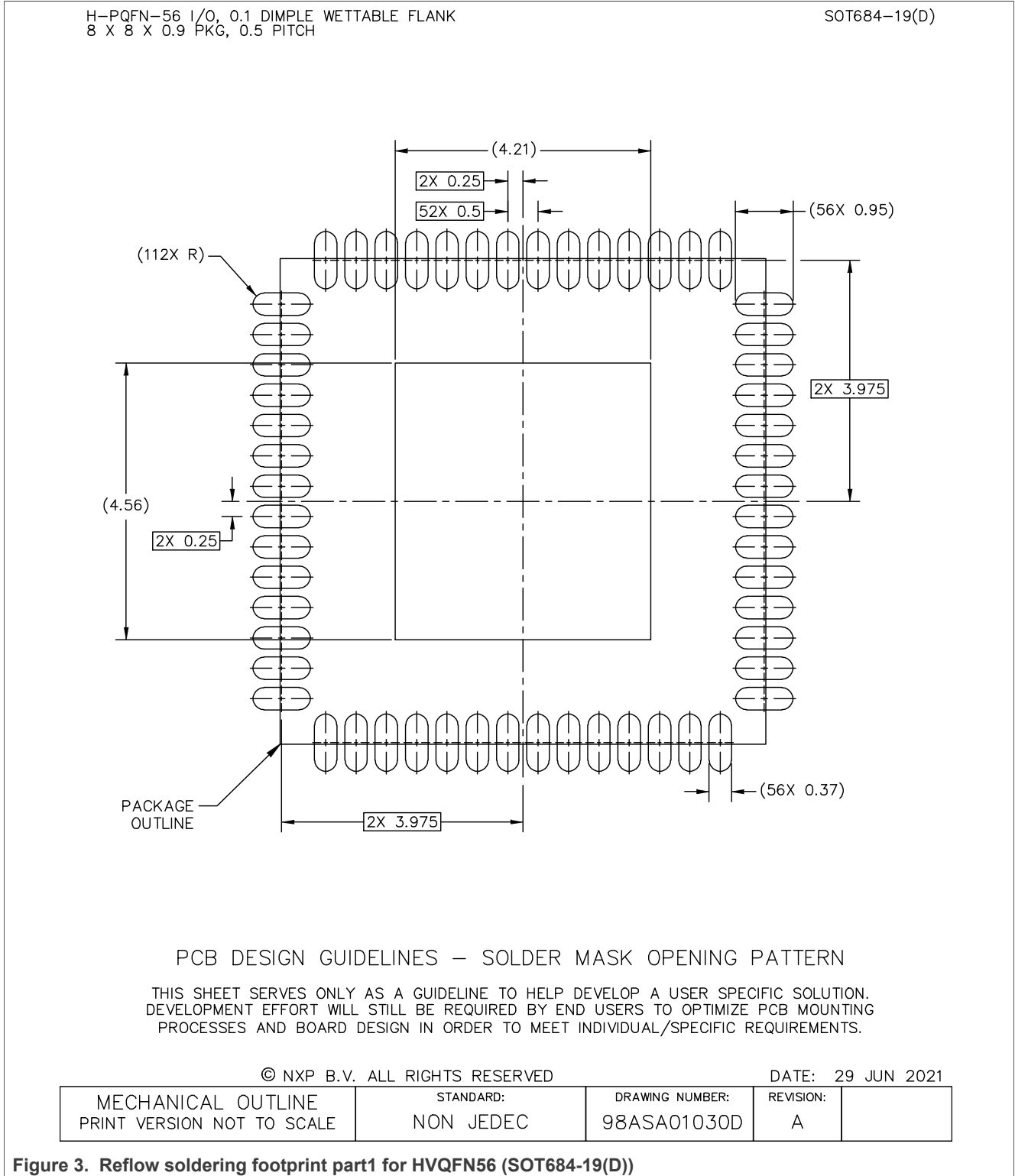
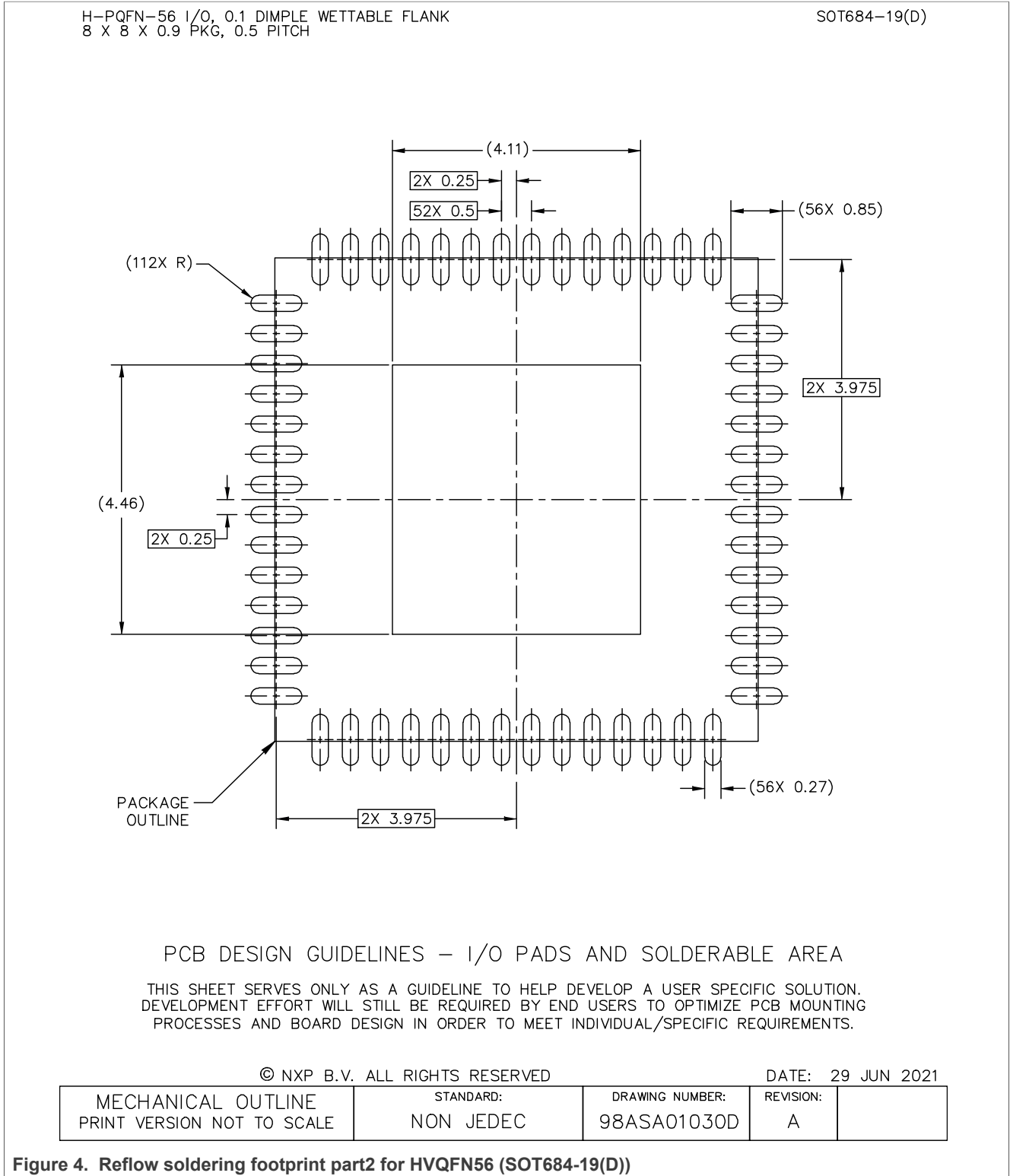
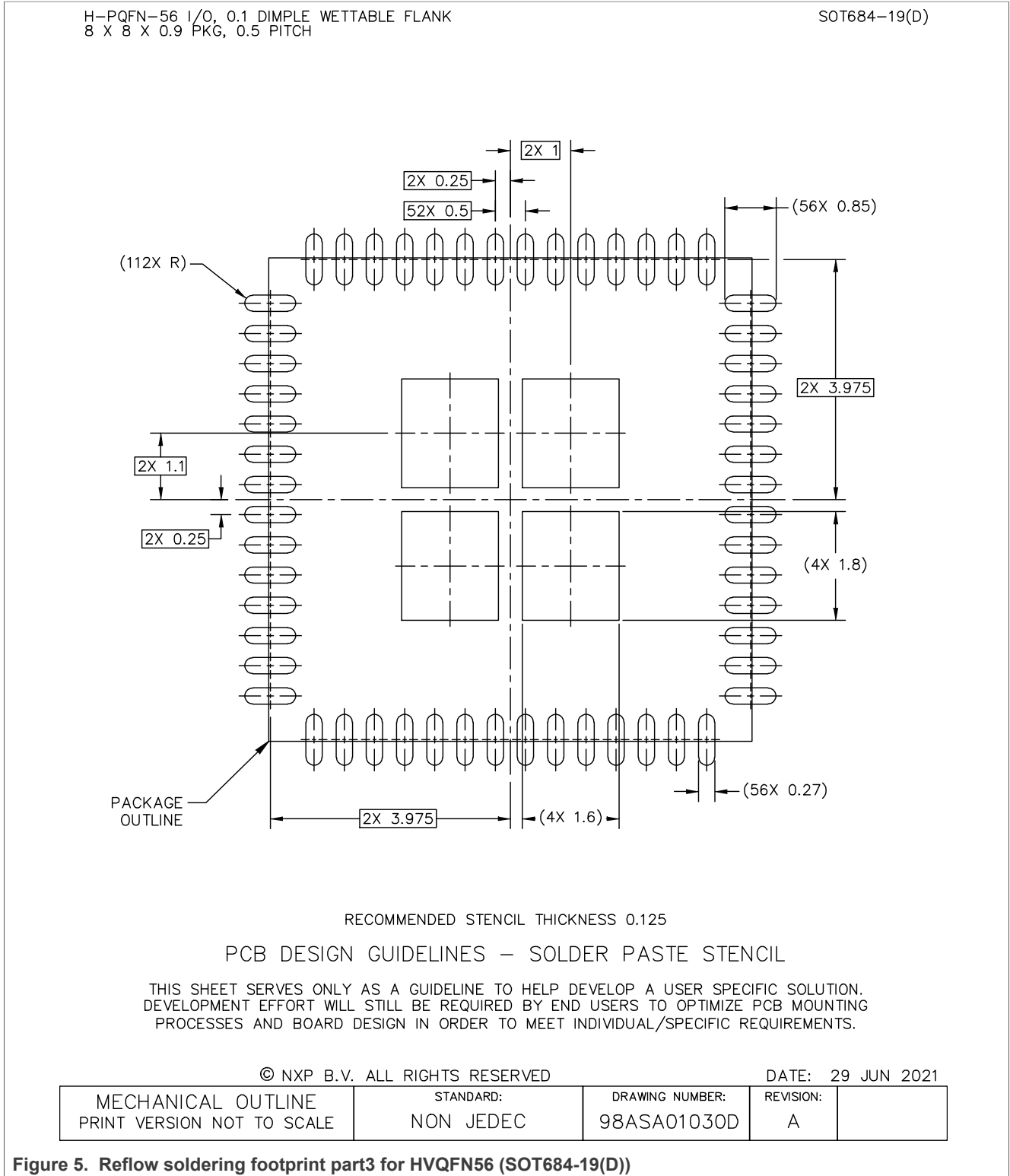


Figure 3. Reflow soldering footprint part1 for HVQFN56 (SOT684-19(D))

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H-PQFN-56 I/O, 0.1 DIMPLE WETTABLE FLANK
8 X 8 X 0.9 PKG, 0.5 PITCH

SOT684-19(D)

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
5. MIN. METAL GAP SHOULD BE 0.2 MM.

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DATE: 29 JUN 2021

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01030D	REVISION: A	
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Figure 6. Package outline note HVQFN56 (SOT684-19(D))

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4 Legal information

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